

# Resistance Reproducibility & Thermal Coefficient of ALD coatings at Argonne

(LAPD project collaboration meeting 06-10-2010)

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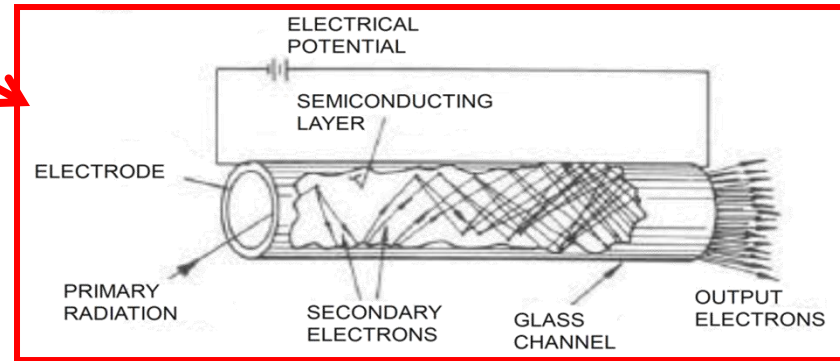
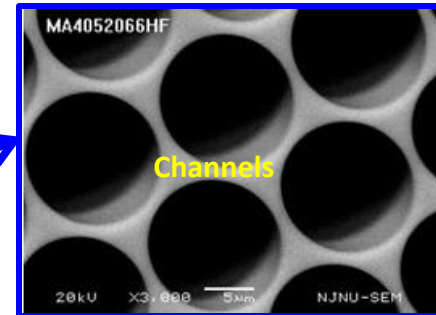
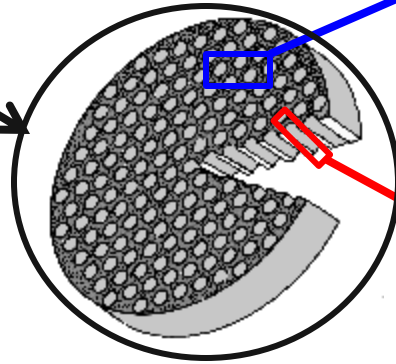
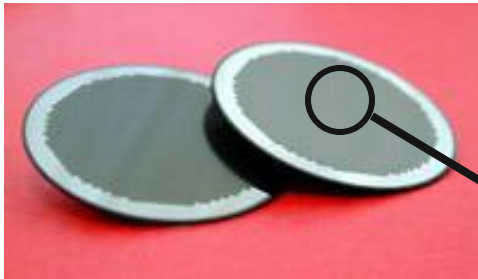
# Outline

- ❑ **LAPD Project: Importance of atomic layer deposition (ALD)**
- ❑ **Development of novel resistive coatings by ALD at Argonne**
- ❑ **Electrical measurements and thermal coefficient study of resistive coatings**
- ❑ **Next plan and Summary**

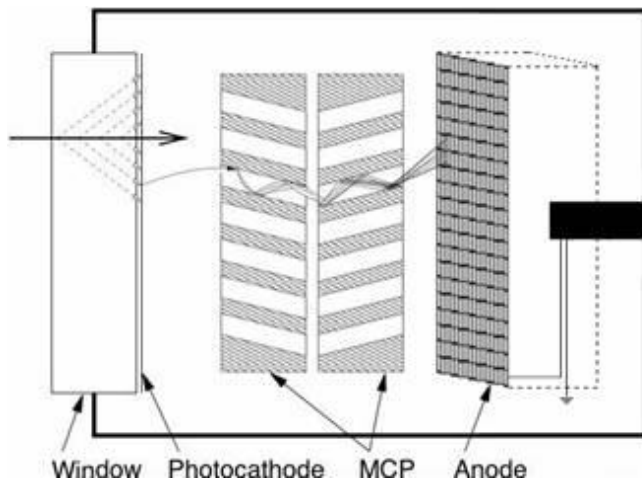
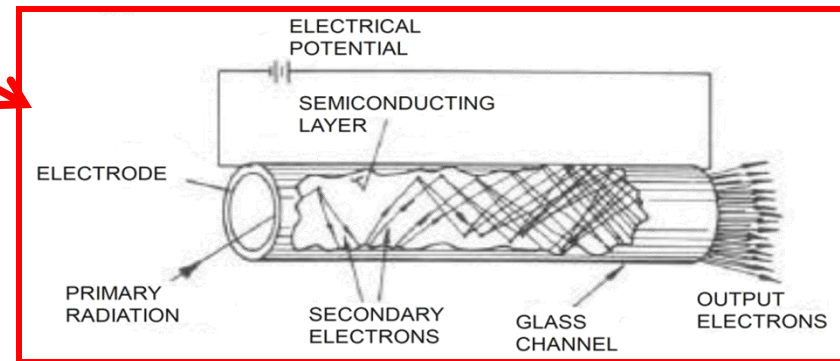
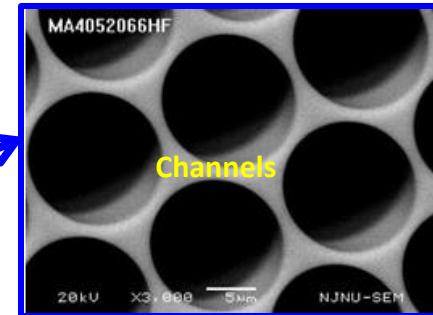
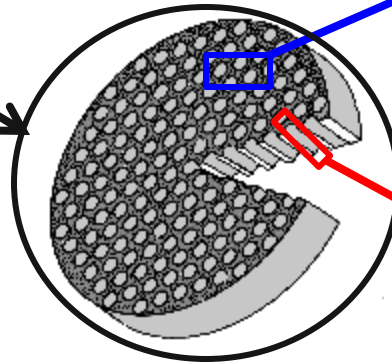
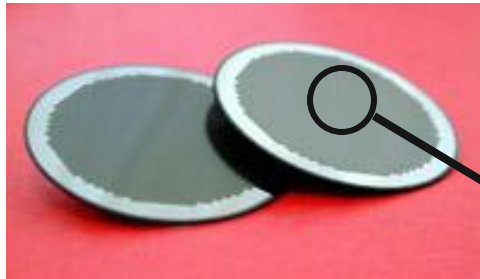
# LAPD project background

- Apply the basic concept of “**micro-channel plate**” (MCP) detectors to the development of large-area photo-detectors (LAPDs) [**8”x8” MCP** ] with quantum efficiencies and gains similar to those of photo-tubes.
- To design and fabricate “**economical**” robust LAPDs that can be tailored for a wide variety of applications that now use photomultipliers.
- LAPD fabrication divided into sub-projects:
  1. Development of higher quantum efficiency photo-cathodes
  2. Use of Atomic Layer Deposition (ALD) to control the chemistry and surface characteristics of resistive and secondary emission surfaces on MCPs
  3. Electronics
  4. Assembly
  5. Testing

# “Microchannel plate” detectors



# “Microchannel plate” detectors



- Continuous-dynode electron multiplier in presence of a strong electric field ( $\sim 1\text{kV}/\text{MCP}$ )
- Electron amplifier ( $\times 10^4\text{-}10^7$ )

# MCP fabrication

## Conventional MCP Fabrication

➤ Draw lead-glass fiber bundle

➤ Slice, polish, chemical etch

➤ Heat in hydrogen

➤ Top/Bottom electrode coating (NiCr)

## Drawbacks


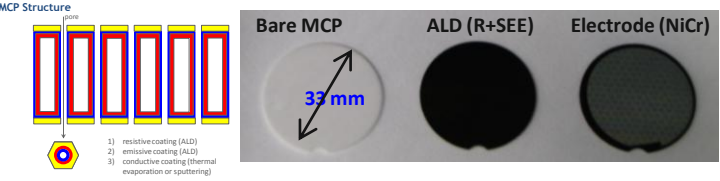
➤ Expensive

➤ Resistance and secondary emission properties are linked

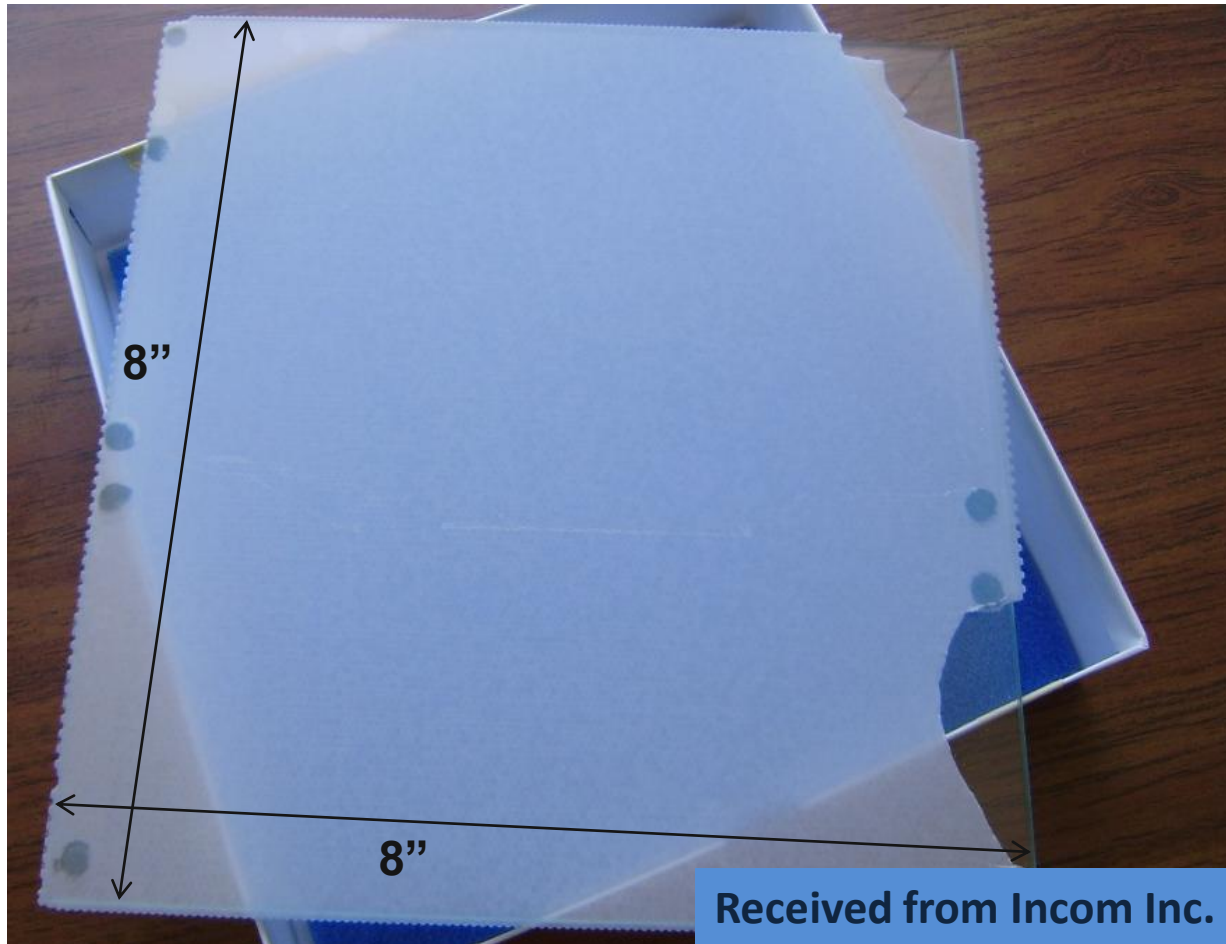
➤ Limited optimize MCP performance for applications where lifetime, gain, substrate size, composition and thermal runaway are important



# MCP fabrication

Conventional MCP Fabrication	LAPD Approach
➤ Draw lead glass fiber bundle	➤ Start with porous, non-lead glass
➤ Slice, polish, chemical etch	➤ ALD (resistive + SEE layer) coating
➤ Heat in hydrogen	➤ Thermal treatment
➤ Top/Bottom electrode coating (NiCr)	➤ Top/Bottom Electrode coating (NiCr)
Drawbacks	Advantages
➤ Expensive	➤ Independent control over composition of Resistive and SEE coating
➤ Resistance and secondary emission properties are linked	➤ Low thermal coefficient of resistance
➤ Limited optimize MCP performance for applications where lifetime, gain, substrate size, composition and thermal runaway are important	➤ Applicable: Ceramics, SiO <sub>2</sub> , plastics, polymers MCPs
	➤ Low cost (No major issue for scale-up with ALD)
	 <p>MCP Structure</p> <ol style="list-style-type: none"> <li>1) resistive coating (ALD)</li> <li>2) emissive coating (ALD)</li> <li>3) conductive coating (thermal evaporation or sputtering)</li> </ol> <p>Bare MCP      ALD (R+SEE)      Electrode (NiCr)</p> <p>33 mm</p>

# Ultimate goal



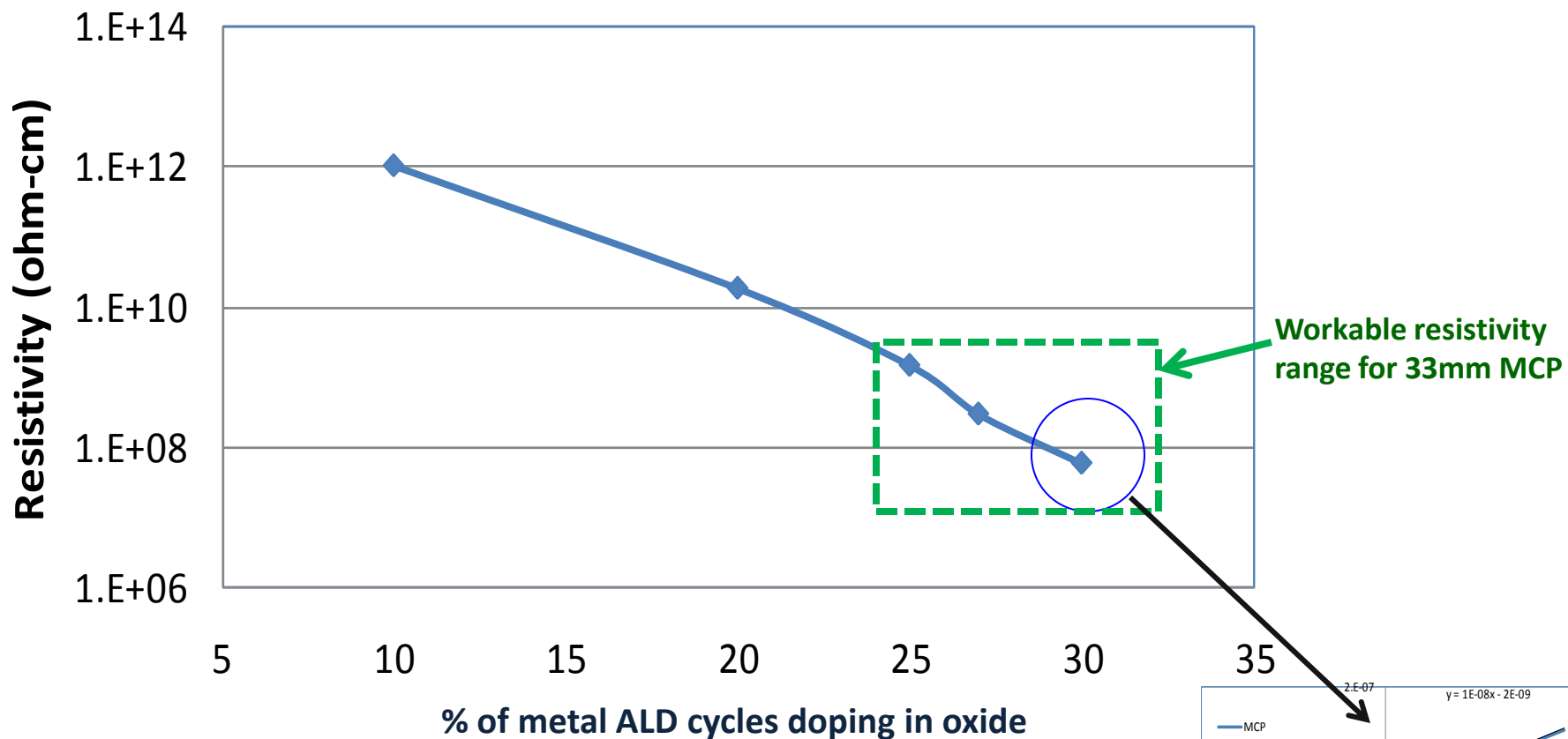
**Create workable 8"x8" MCP with ALD**



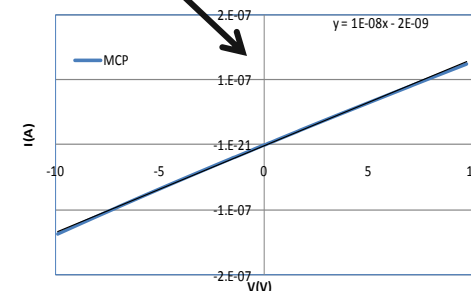
# Materials selection for functionalisation of MCPs

- **Secondary electron emission coating:**
  - Al<sub>2</sub>O<sub>3</sub>, MgO, Diamond, MgF<sub>2</sub>, .....
- **Resistive coating: Composites of Metal and insulator**
  - Variety of material
  - Reliability
  - Scaling and Cost
- **Why ALD process?**
  - Atomic level control over composition, thickness,
  - Excellent uniformity and **conformal coating on very high aspect ratio (>98%)**
  - Large area deposition, batch processing (low cost)
- **Developed workable few novel resistive coatings by ALD process:**
  - Submitted patent application
  - Here after named as Chemistry-1, 2, ....
  - Tested with different ALD grown SEE layers

# ALD coating on MCP: Chemistry #1 Resistivity



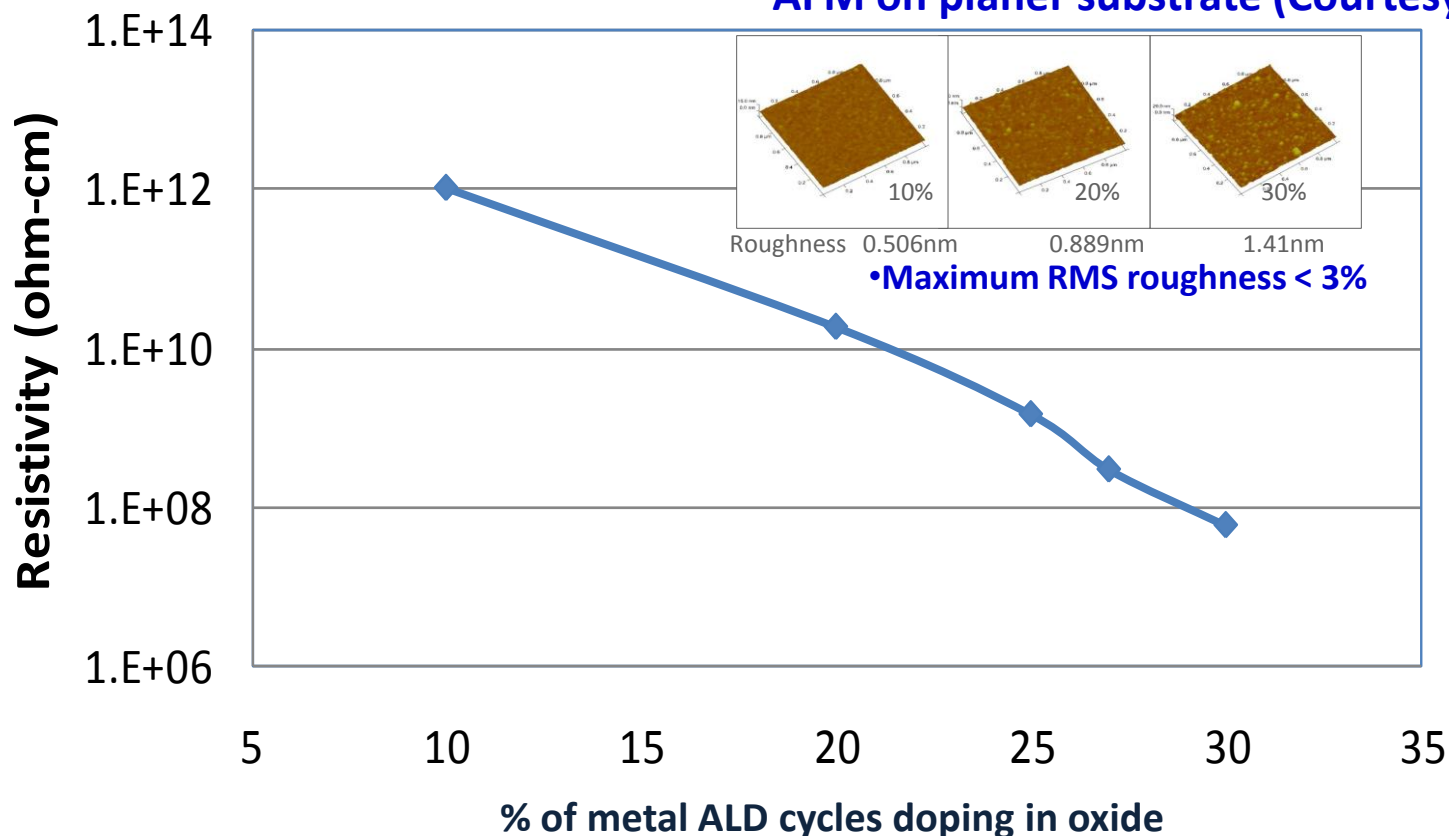
- Good control over resistivity
- Several MCP pairs shows good “Gain data”
  - Matt Wetstein will present status later



• Linear I-V on MCP

# ALD coating on MCP: Chemistry #1

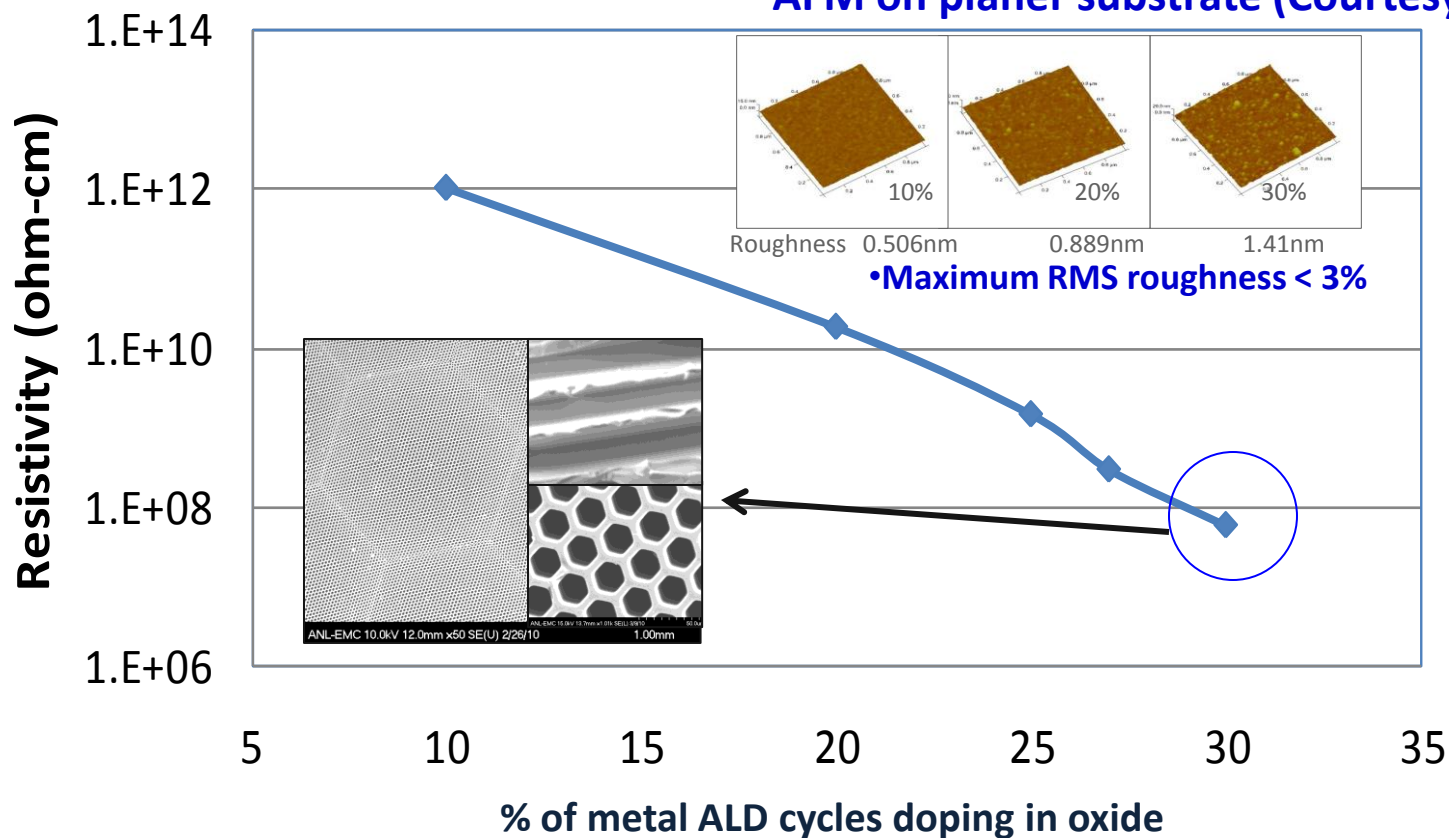
AFM on planer substrate (Courtesy: Hau Wang)



- Uniform and smooth ALD coating on Si(100) surface

# ALD coating on MCP: Chemistry #1

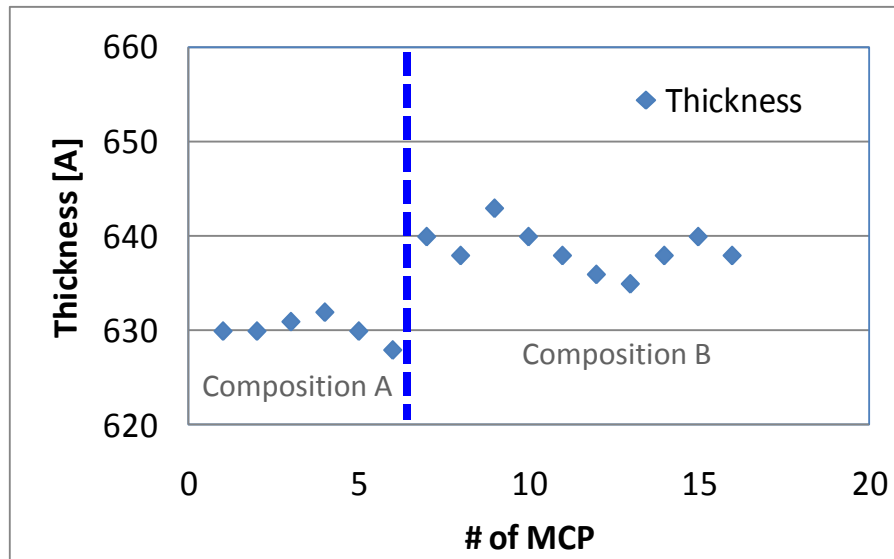
AFM on planer substrate (Courtesy: Hau Wang)



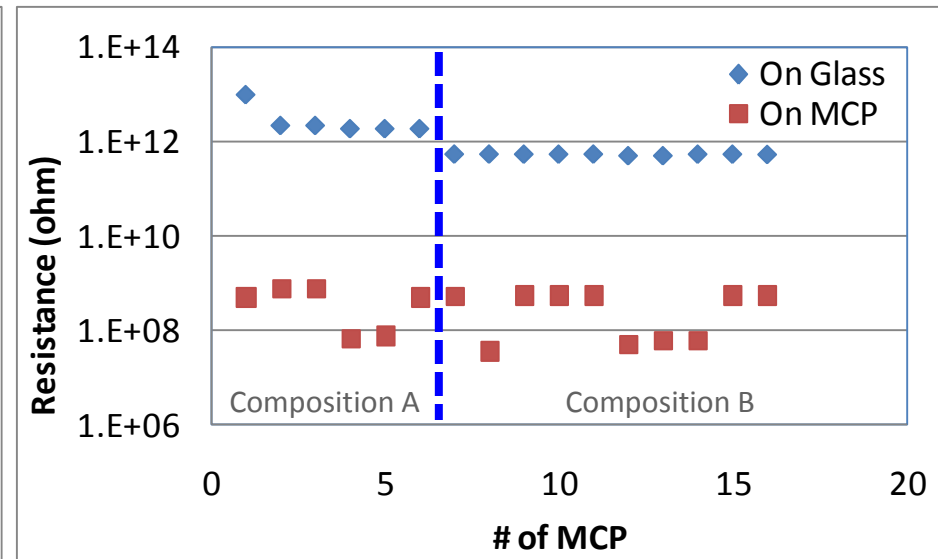
- Uniform and smooth ALD coating pores of MCP

# Reproducibility: ALD Chemistry #1

Thickness on Si(100)

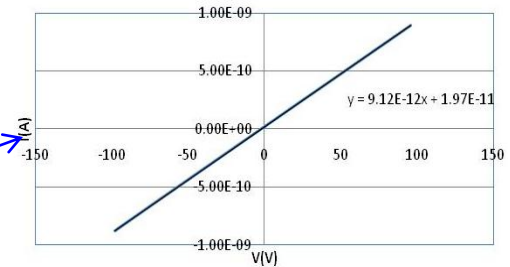
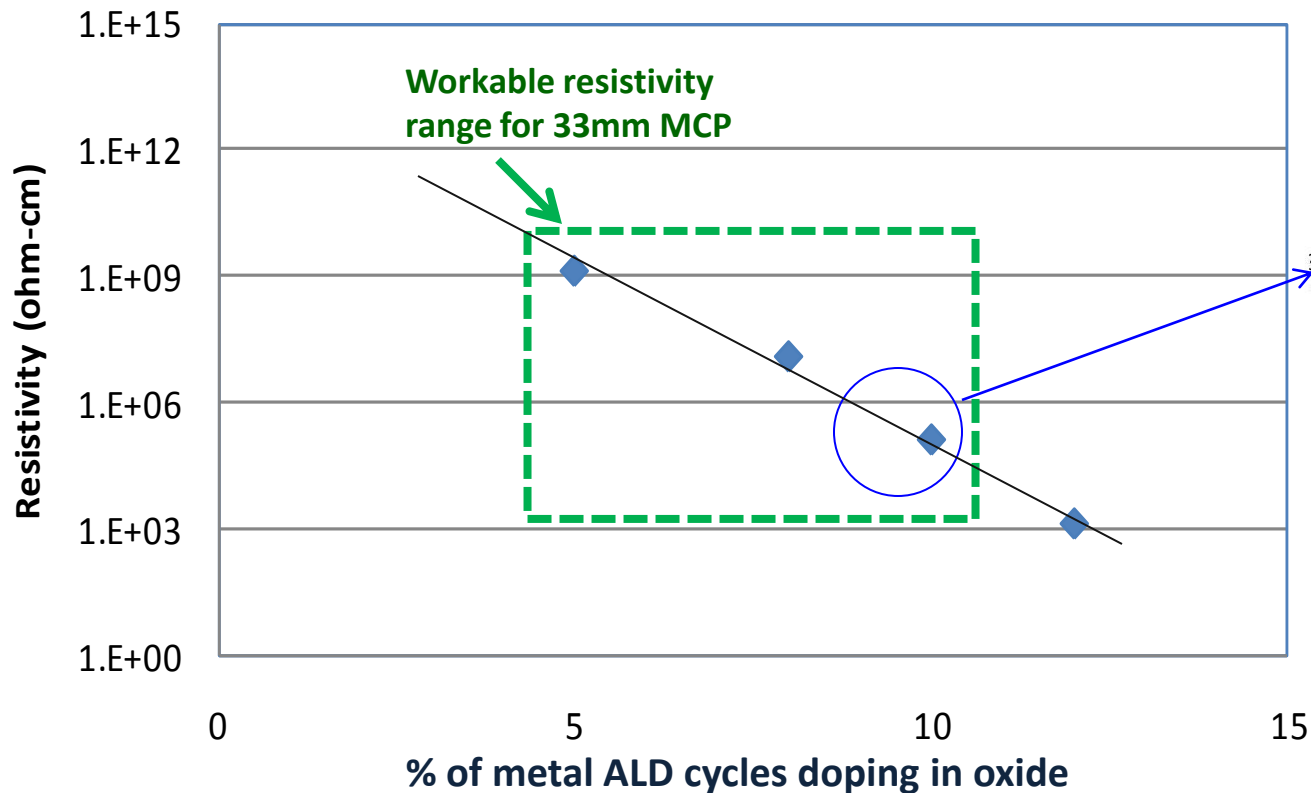


Resistance



- Excellent reproducible thickness and resistance on Glass
- Resistance variation on MCP cause by electrode “end spoiling”
  - Electrode coating plays very crucial role and need reliable source

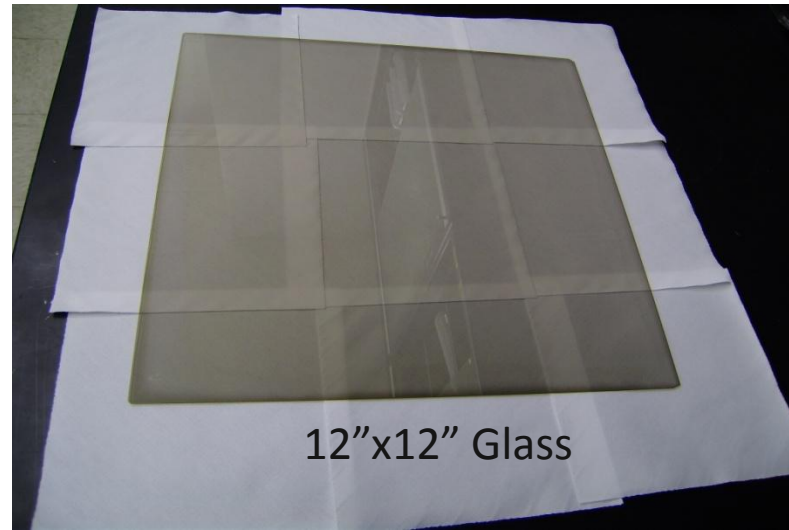
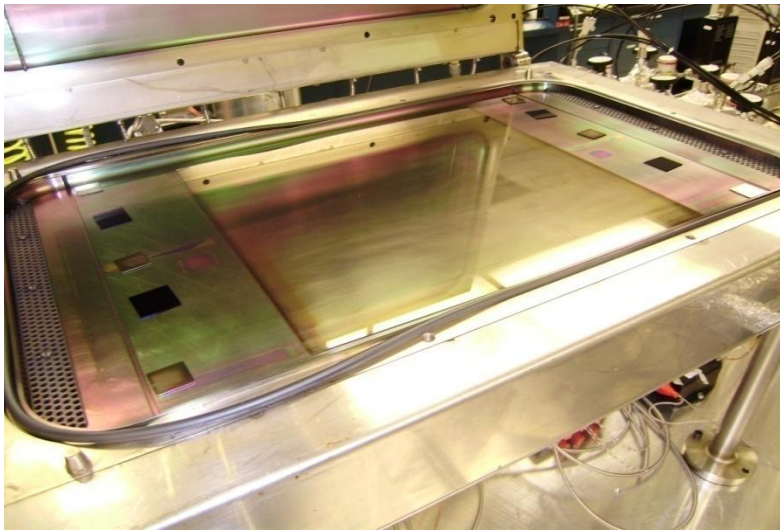
# Resistivity of ALD coating on Glass: Chemistry #2



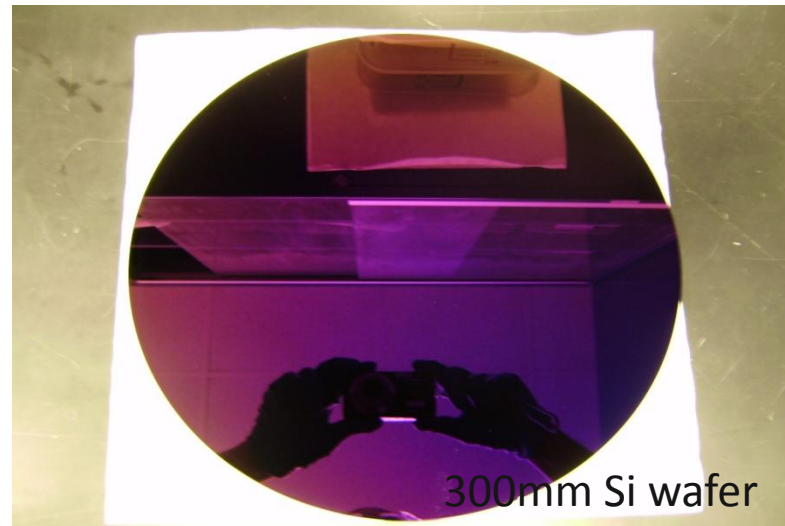
•Linear I-V on Glass

- Better control process than chemistry 1: uniform and smooth ALD coating
- Similar resistivity range (like chemistry-1) with low % of metal doping
- Process tested on large substrates capable ALD reactor

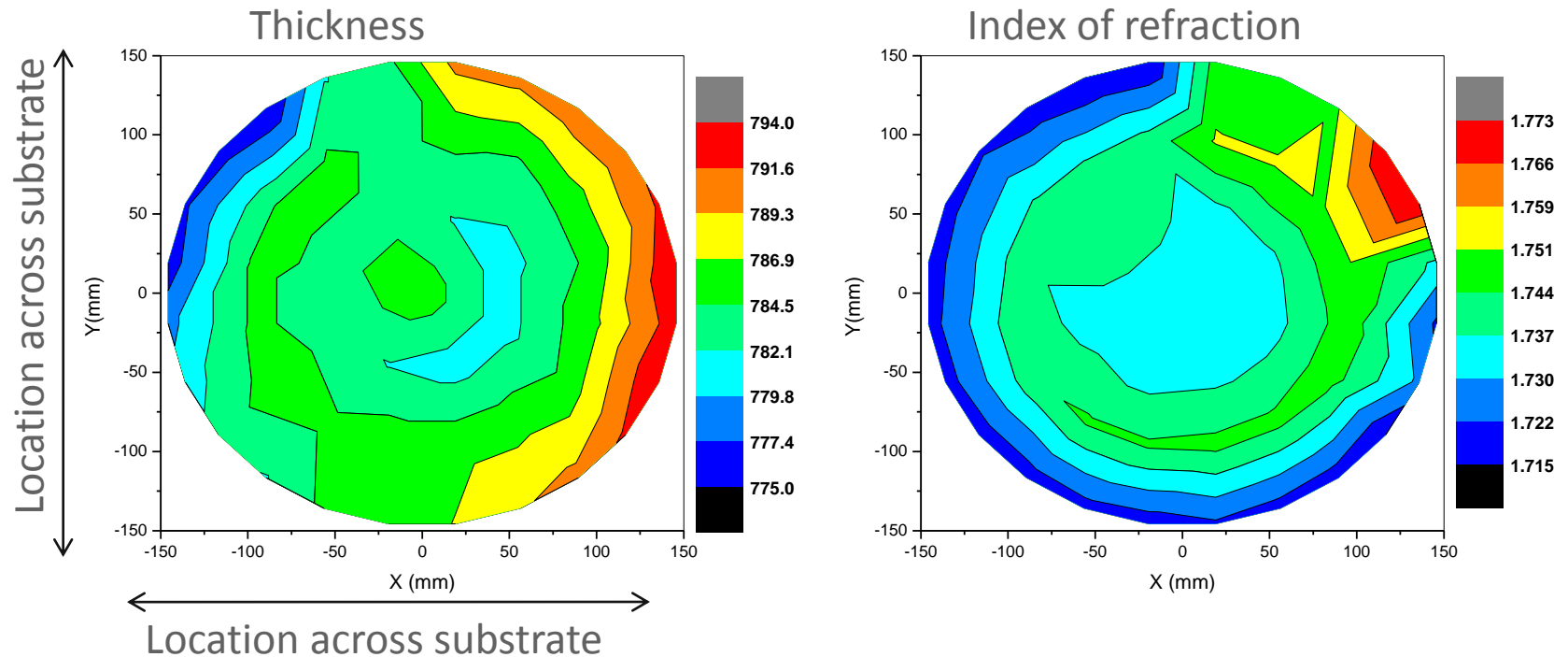
# Process scale-up test: ALD chemistry #2



**Resistive coating process tested  
on custom made large substrate  
processing ALD reactor**



# Large substrate testing: ALD Chemistry #2

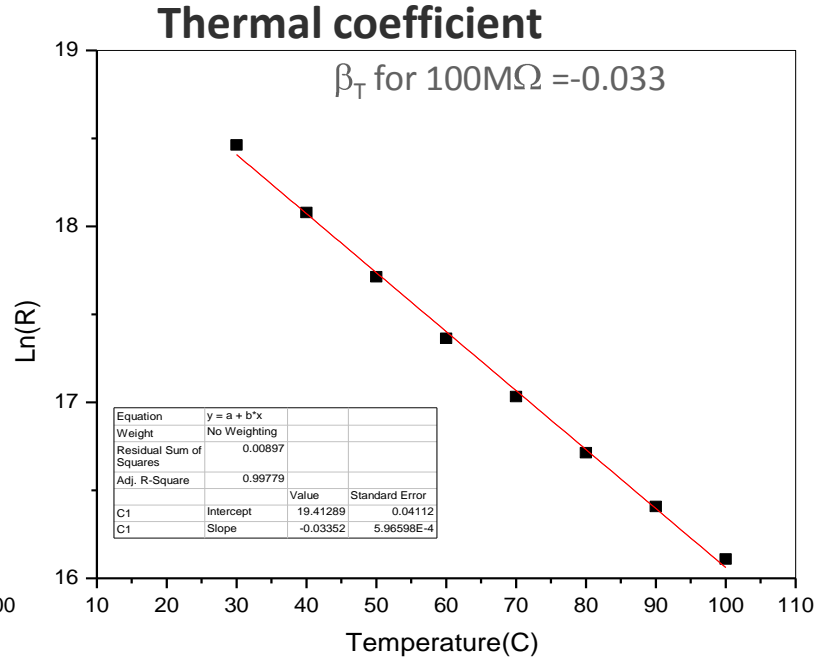
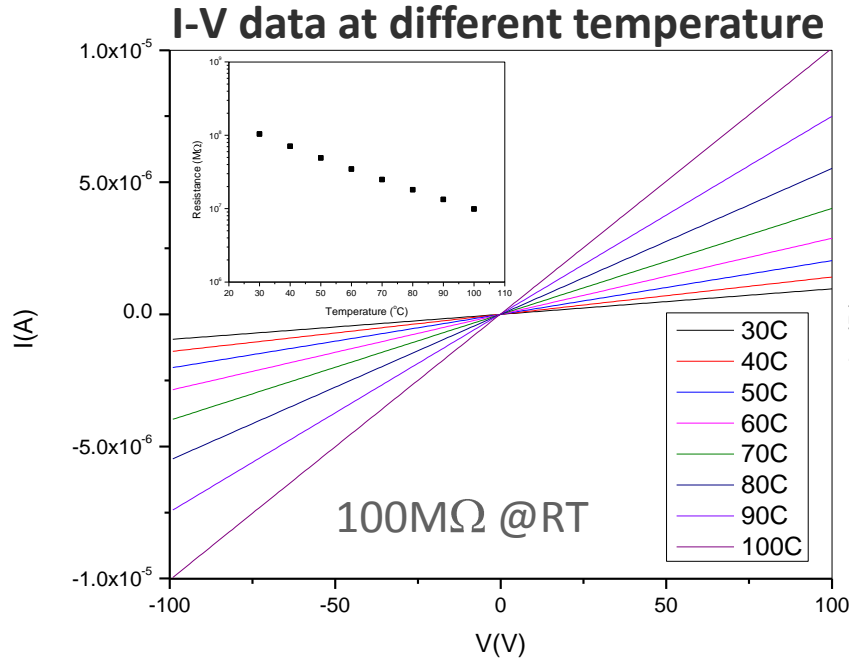


Item	Thickness [Å]	Index of refraction (n)
Minimum	775	1.72
Maximum	794	1.77
Average	785	1.73
% STDV ( $1\sigma$ )	<b>0.57</b>	<b>0.84</b>



# Thermal characteristics: ALD of Chemistry #2 on MCP

Thermal coefficient of resistance =  $R_{mcp} = R_0 \exp(-\beta_T(T_{mcp} - T_0))$



MCP	Resistance (air)	$\beta_T$
Commercial (~0.7 cm <sup>2</sup> )	6.5GΩ	-0.0451
With ALD Chemistry-1	500MΩ	-0.0337
With ALD Chemistry-2	100MΩ	-0.0335

- Linear I-V characteristic for all temperature
- ALD coated MCPs shows lower  $\beta_T$  → Reduced thermal runaway

# Summary

- 1) Developed several novel ALD of resistive coating processes
  - Excellent control over thickness, uniformity, resistance & thermal coefficient
- 2) Demonstrated the scalability of the resistive ALD process
- 3) Contact electrode plays crucial role in resistance tuning
  - Need attention especially for 8"x8" MCP
- 4) Achieved all Year 1 and some Year 2 LAPD project goals for ALD group

# Next plan

- Gain test for several ALD functionalized MCP
- MCPs are extremely sensitive to moisture → Resistance optimization in vacuum
- Testing of alternative ALD grown SEE layer
- Process qualification on commercial ALD system  
-(Beneq TFS 500, Tool installation is in progress)
- Functionalization of 8"x8" MCPs on Beneq ALD system
- After patent, write few publications

😊 Thank you for your attention. 😊